

Abstract of the Disclosure:

A shielding device includes optical and/or electrical shielding disposed on the side of the integrated circuit in the semiconductor chip facing the substrate. Preferred configurations use an SOI substrate with the integrated circuit in the body silicon layer and the insulator layer as a device for optical shielding from the bulk silicon layer. Electrical conductors may be present as an optical and electrical shielding device in the bulk silicon layer, and they may be connected to the circuit using vias.

GLM/nt